

■ Description

This revolutionary package design allows the lighting designer to reduce the number of LED required and provide a more uniform and unique illuminated appearance than with other LED solutions.

This is possible through the efficient optical package design and high-current capabilities.

■ Features

- High Flux Output.
- Low Thermal Resistance.
- Low Profile.

■ Applications

- Indicator.
- General use.

■ Absolute Maximum Ratings (at Ta=25°C)

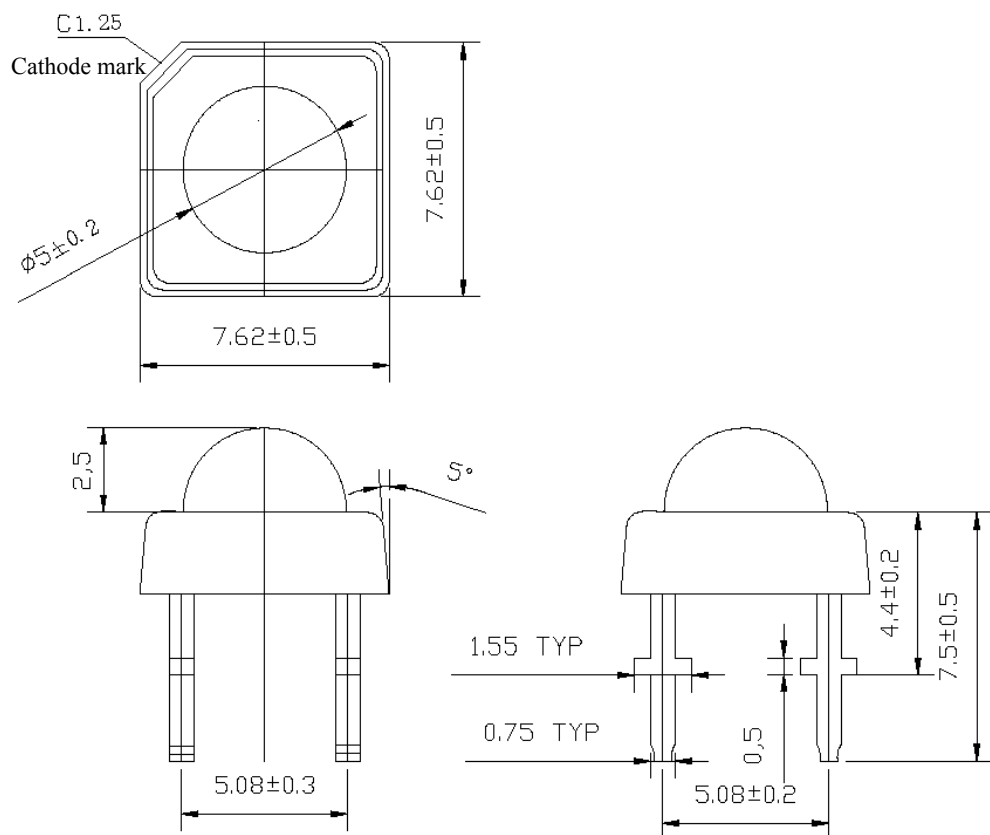
Parameter	Symbol	Maximum Rating	Unit
Power Dissipation	P _D	120	mW
Forward Current	I _F	25	mA
Peak Forward Current (Pulse width ≤ 100 μS duty ≤ 1/10)	I _{FP}	100	mA
Reverse Voltage	V _R	5	V
Operation Temperature	Topr	-25 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +100	°C
Electrostatic Discharge	ESD	150	V
Lead Soldering Temperature (2mm from the case t ≤ 5S)	Tsol	260	°C

Basic Characteristics

 $T_a=25^{\circ}\text{C}$

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F=20\text{mA}$	--	3.2	4.0	V
Reverse Current	I_R	$V_R=5\text{V}$	--	--	50	μA
Dominant Wavelength	λ_D	$I_F=20\text{mA}$	--	470	--	nm
Peak Wavelength	λ_P	$I_F=20\text{mA}$	--	468	--	nm
Spectral Bandwidth	$\Delta\lambda$	$I_F=20\text{mA}$		35	--	nm
Luminous Intensity	I_V	$I_F=20\text{mA}$		1400	1800-	mcd
50% View Angle	$2\theta_{1/2}$	$I_F=20\text{mA}$		90	--	deg

Package Dimensions



Notes: without special declared, the tolerance is $\pm 0.25\text{mm}$

■ Typical Electrical / Optical / Characteristics Curves

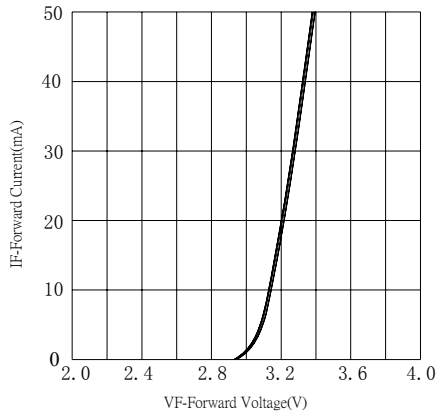


Fig.1 Forward Current vs.Forward Voltage

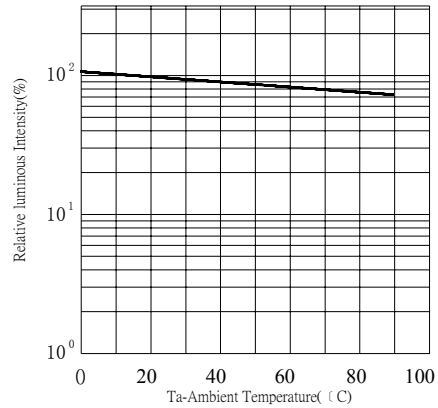


Fig.2 Relative luminous Intensity vs.Ambient Temperature

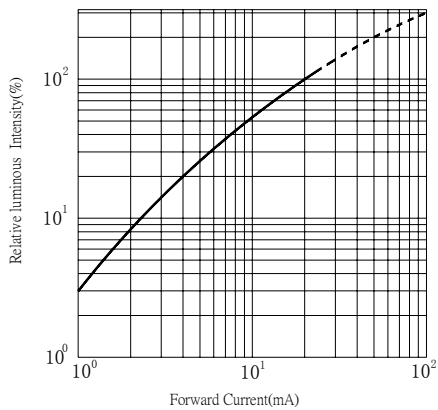


Fig.3 Relative luminous Intensity vs.Forward Current

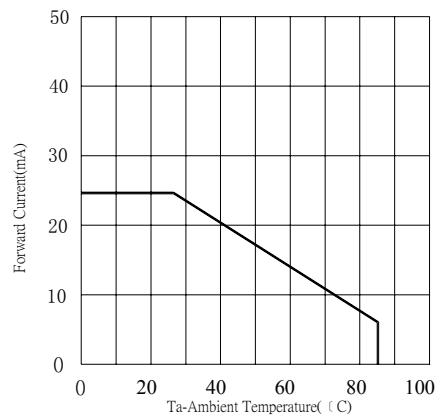


Fig.4 Forward Current vs.Ambient Temperature

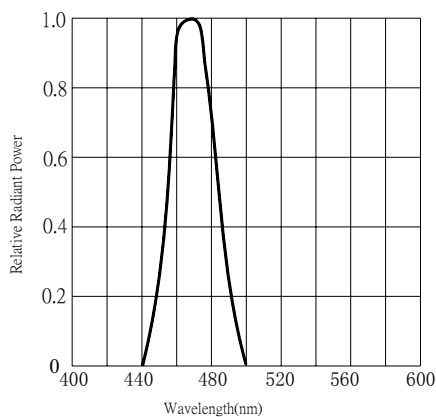


Fig.5 Relative Radiant Power vs.Wavelength

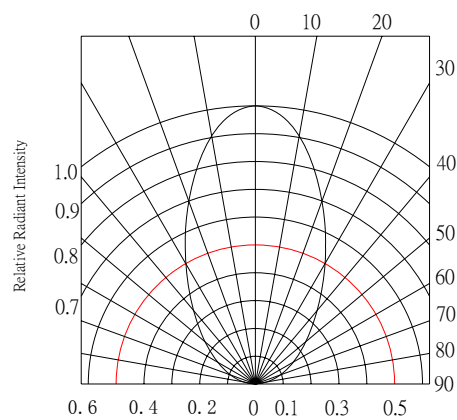


Fig.6 Relative Radiant Intensity vs.Angular Displacement